

APPENDIX-CLAIM 1 AS AMENDED- MARKED-UP VERSION

1. (Amended) An electronic structure comprising:

a first dielectric layer of polymeric material having a first top surface;  
a second dielectric layer of polymeric material on said first top surface of said first dielectric layer of polymeric material, having a second top surface, said second layer of polymeric material also having trench features therein; and electrically conductive material deposited in said trench features forming electrically conductive circuit lines being substantially flush with said second top surface of said second dielectric layer of polymeric [dielectric] material, wherein said polymeric material is at least one member selected from the group consisting of thermoplastic resin and thermosetting resin.